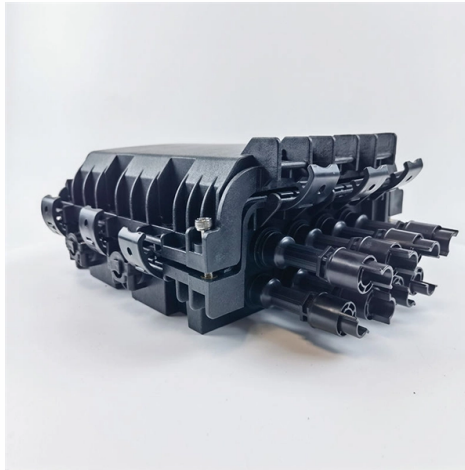


OCP produces optical modules



AI Overview

OCP manufactures a wide range of optical modules, including transceivers, transponders, transmitters, and receivers for high-speed networking and data center applications.

Overview of OCP Optical Modules

OCP (Optical Communication Products, Inc.) was founded in 1991 and specializes in fiber-optic communication components and subsystems. Their optical modules support Ethernet, SONET/SDH, Fibre Channel, and ESCON applications, packaged in SFP, SFF, and GBIC formats. OCP's product line includes transceivers, transponders, transmitters, receivers, arrays, and CWDM solutions, designed for both commercial and military-grade applications.

Key Product Categories

- Transceivers:** Compact modules that convert electrical signals to optical signals and vice versa, supporting high-speed data transfer in data centers and enterprise networks.
- Transponders:** Modules like the PTC-48 OC-48 series combine optical transceiver functionality with SONET/SDH electronic multiplexing and de-multiplexing, enabling integration of multiple lower-speed signals into a single high-speed optical output.
- Transmitters and Receivers:** Standalone modules for sending and receiving optical signals over fiber networks, often used in metropolitan area networks and high-speed premises networks.
- CWDM Solutions:** Coarse Wavelength Division Multiplexing modules for increasing fiber capacity by transmitting multiple wavelengths over a single fiber.

OCP in the Open Compute Project (OCP) Ecosystem

OCP is also associated with the Open Compute Project Foundation, which promotes open-source hardware for data centers. Companies like ColorChip have contributed 100G CWDM4 QSFP28 Lite transceivers to the OCP community, offering low-power, compact, and interoperable solutions for high-bandwidth data center applications. Additionally, OCP supports next-generation optical modules such as OSFP and QSFP devices capable of up to 1.6 Tbps, with innovations in liquid cooling to overcome thermal limitations in high-density AI and HPC environments.

Article Content

Progress in Research on Co-Packaged Optics

In the 5G era, the demand for high-bandwidth computing, transmission, and storage has led to the development of optoelectronic interconnect technology. This technology has evolved from

Introducing Facebook OCP 200G FR4 Optical Transceiver

The 200G FR4 OCP specification is based on IEEE 200GBASE-FR4 as defined in IEEE 802.3 bs. It is optimized considering the actual operating conditions of data centers to positively

Samtec Mid-Board Optical Transceiver Solutions (OFC 2025)

Samtec had several live-product optical demonstrations at OFC 2025, including PCIe 5.0 over fiber, co-packaged chip systems, the new Halo low-profile and rugged transceiver, and the new Fireblade

OCP Intros OC48 SFP for DWDM

OCP's OC-48/STM-16 DWDM SFP multi-rate transceivers will be on display at the 31st European Conference on Optical Communications (ECOC 2005) on September 25-29, 2005 at the

OCP Market Intelligence Function

Scale-Up Diversity Industry rapidly evolving to three protocols for scale-up: Ethernet, UALink, Nvlink CPO based Optical interconnects provide an alternative to mega-rack architectures and enable much

Samtec Demonstrates New 1.6 Tbps OCP OAI EXP Module at SC24

It incorporates 16 FireFly optical transceivers with 1.6 Tbps aggregate throughput. The FireFly module is protocol agnostic, including support for Ethernet, PCIe, and CXL over optics.

Open Compute Products

Optimize your data center with Legrand's Open Compute Project (OCP) products. Explore our ORV3 racks, OCP power shelves, AC shelves, and power supply units designed for efficiency and scalability.

Ethernet Network Interface Card vs. IB Network Interface Card

Similar to a small CPU, the controller processes the received data. Network card ports: Typically, these ports directly connect to Ethernet cables or optical modules, enabling the

What is Co-Packaged Optics?

Learn how co-packaged optics is reshaping data center networks by slashing power use and unlocking massive bandwidth for next-gen AI performance.

Co-Packaged Optics — a deep dive | APNIC Blog

OFC 2025 made one thing clear: The transition to Co-Packaged Optics (CPO) switches in data centres is inevitable, driven primarily by the power savings they offer. From Jensen Huang

Open Compute Project launches Optical Circuit Switching (OCS ...

The Open Compute Project Foundation (OCP) – the nonprofit organization focused on advancing hyperscale innovations – has announced the formation of a new Optical Circuit Switching

Home » Open Compute Project

In shaping the future, OCP will continue to invest in strategic initiatives that prepare the IT ecosystem for major changes, such as AI & ML, optics, sustainable data center solutions, advanced power

Intel® Shows OCI Optical I/O Chiplet Co-packaged with CPU at

Christian Urricariet is Head of Product Marketing for Silicon Photonics at Intel. At the Optical Fiber Conference (OFC) in San Diego on March 26-28, 2024, Intel demonstrated our

OCP to create an open stack for photonic networking

The Open Compute Project Foundation (OCP) has unveiled its latest project: an open-standard networking switch powered by photonics. The Optical Circuit Switching (OCS) Subproject

Open Compute Project (OCP) Solutions

Active Optics Cable Assemblies Sliver Internal Cabled Interconnects CDFP Connectors, Cages & Cable... OCP Power Distribution Solutions With our plug

Meta 400G FR4 Optical Transceiver Specification for OCP_Rev0.1

2.2 Overview The 400G-FR4 OCP optical specification is based on IEEE 400GBASE-FR4 specification as defined in IEEE 802.3 cu. Similar to 200G-FR4 OCP specification, it is optimized considering both

OCP DEBUTS OC-48 OPTICAL TRANSPONDER PRODUCT FAMILY.

Optical Communication Products Inc. (Nasdaq:OCPI), a manufacturer of fiber optic subsystems and modules for metropolitan area networks and high-speed premises networks, has

Intel Demonstrates First Fully Integrated Optical I/O Chiplet

Intel Corporation's Integrated Photonics Solutions (IPS) Group has demonstrated the industry's first fully integrated optical compute interconnect (OCI) chiplet co-packaged with an Intel

CPO (Co-Packaged Optics): A Key Technology Path for Optical ...

At this year's OCP Global Summit, "Co-Packaged Optics (CPO)" became a frequently mentioned buzzword. With the continuous expansion of ultra-large model training scale and AI

OPTICAL CIRCUIT SWITCHING FOR AI AND

OCS devices establish direct photonic connections between endpoints without requiring optical-electrical-optical (OEO) conversion. Operating purely in the optical domain is one of the key

Samtec will showcase interconnect solutions at OCP Summit

At this year's OCP Global Summit, Samtec will introduce the FireFly OCP OAI EXP Module. This module features 16 FireFly optical transceivers, delivering an aggregate throughput of

iPronics and Lumentum Lead the Efforts to Standardize OCS

This initiative brings together some of the most important companies in the technology sector, including Google, Microsoft, Coherent Corp., and other prominent players, with the aim of

Scaling Open Compute Project (OCP) Optics Standards

Master the engineering realities of Open Compute Project (OCP) optics standards. Learn how to troubleshoot PAM4 signal integrity, DSP thermal throttling, and CMIS failures.

Broadcom CPO: Highest Power Efficiency and Bandwidth Density

Co-Packaged Optics (CPO) is an advanced integration of optics and silicon on a single packaged substrate addressing interconnect bandwidth and power challenges.

A Deep Dive into Optical Layer Protection (OLP, OMSP, OCP)

Let's discover the essentials of Optical Layer Protection in DCI with OCP, OMSP, and OLP technologies, ensuring robust data transmission security in the modern era.

Contact Us

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